What is claimed is:

1. Ceramic powder having a multiple peak-frequency type particle size distribution which has at least two peaks, as determined according to the laser diffraction-scattering type particle size distribution analyzer, wherein the maximum particle size observed for the first peak falls within the range of from 12 to 30μm; wherein the maximum particle size observed for the second peak falls within the range of from 2 to 7μm; wherein the content of the particles having a particle size of greater than 7μm and less than 12μm is not more than 18% (including 0%); and wherein the ratio (F2/F1) of the frequency value F2 of the maximum particle size observed for the second peak to the frequency value F1 of the maximum particle size observed for the first peak ranges from 0.5 to 1.3.

2. The ceramic powder of claim 1, having a particle size distribution having an additional third peak and the maximum particle size observed for the third peak falls within the range of from 0.1 to 0.8μm.

3. The ceramic powder of claim 1 or 2, wherein the amount of the oversize particles as determined using the JIS Standard Sieve of 53μm is not more than 0.5% by mass (including 0% by mass).

4. The ceramic powder of any one of claims 1 to 3, wherein the ceramic powder is silica powder.

5. A composition comprising at least one of a resin and rubber; and ceramic powder of any one of claims 1 to 4 incorporated into the resin and/or rubber.

6. A semiconductor-sealing material comprising the composition of claim 5 wherein at least one of the resin and the rubber is an epoxy resin.

Claims

1. Spherical amorphous silica powder having a multiple peak-frequency type particle size distribution which has at least two peaks, as determined according to the laser diffraction-scattering type particle size distribution analyzer, wherein the maximum particle size observed for the first peak falls within the range of from 12 to 30 μm; wherein the maximum particle size observed for the second peak falls within the range of from 2 to 7 μm; wherein the content of the particles having a particle size of greater than 7 μm and less than 12 μm is not more than 18% by mass (including 0% by mass); and wherein the ratio (F2/F1) of the frequency value F2 of the maximum particle size observed for the second peak to the frequency value F1 of the maximum particle size observed for the first peak ranges from 0.5 to 1.3.

2. The spherical amorphous silica powder of claim 1, having an additional third peak and the maximum particle size observed for the third peak falls within the range of from 0.1 to 0.8 μm.

3. The spherical amorphous silica powder of claim 1 or 2, wherein the amount of the oversize particles as determined using the JIS Standard Sieve of 53 μm is not more than 0.5% by mass (including 0% by mass).

4. A composition comprising at least one of a resin and rubber; and spherical amorphous silica powder of any one of claims 1 to 3 incorporated into the resin and/or rubber.

5. A semiconductor-sealing material comprising the composition of claim 4 wherein at least one of the resin and the rubber is an epoxy resin.